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[10191/3399]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s) : Klaus BREITWCHWERDT
Serial No. : 10/691,108
Filed : October 22, 2003
For : DEVICE AND METHOD FOR ANISOTROPIC PLASMA
ETCHING OF A SUBSTRATE, PARTICULARLY A
SILICON ELEMENT

Examiner : Lan Vinh
Art Unit : 1765
Confirmation No. : 4772

I hereby certify that this correspondence is being deposited with the
United States Postal Service with sufficient postage as first class mail in
an envelope addressed to: Mail Stop Amendment, Commissioner for
Patents P.O. Box 1450,
Alexandria, VA 22313-1450 on

Date: June 8, 2006 Reg. No. 42,194
Signature: Chih Lin

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL

SIR:

Enclosed herewith for filing in the above-identified patent application is a Response.

Applicants respectfully request a three-month extension of time in which to respond
to the Office Action mailed January 5, 2006 for which a three month response period expiring
on April 5, 2006 was set. The three month extended period expires on July 5, 2006.

Please charge the extension fee of \$1,020.00, and any additional fees that may be
required to **Deposit Account No. 11-0600**. A duplicate copy of this transmittal letter is
enclosed for that purpose.

Respectfully submitted,

Dated: June 8, 2006

By: Gerard A. Messina
Gerard A. Messina
(Reg. No. 35,952)
P.N. 42,194

KENYON & KENYON LLP
One Broadway
New York, New York 10004
(212) 425-7200